

In the Specification

Pursuant to 37 C.F.R. §1.121, the following rewritten paragraph is shown in Appendix A with notations to indicate the changes made.

Please replace the paragraph beginning at page 15, line 17, with the following rewritten paragraph.

In order to increase the thermal stability of an instant setting adhesive composition, a thermal stabilizer can be added to the adhesive composition. Preferably, the thermal stabilizer is a compound selected from the group of an alkyl 2-cyano-2,4-pentadienoate; an alkyl 2-cyano-2,4-hexadienoate; an itaconic anhydride (e.g., U.S. Patent No. 3,984,749 to Konigm); a maleic anhydride (e.g., U.S. Patent No. 3,832,334 to O'Sullivan, et al.); a substituted naphasultone (e.g., U.S. Patent No. 5,424,343 to Attarwala); a di- α -cyanopentadienoate disiloxane (e.g., U.S. Patent No. 5,386,047 to Nakos et al.); a sulfur-containing compound such as a sulfoxide, a sulfonate, a sulfinate, etc. (e.g., U.S. Patent No. 5,328,944 to Attarwala et al.), an aromatic compound substituted with at least three electron withdrawing groups (e.g., U.S. Patent No. 5,288,794 to Attarwala); a bifunctional monomer (e.g., a (meth)acrylic acid ester, an aliphatic polyol, an aromatic polyol, to name a few); an unsaturated ester of 2-cyanoacrylic acid (e.g., U.S. Patent No. 3,142,698 to Benjamin et al., and U.S. Patent No. 3,825,580 to Kato et al.); and mixtures thereof. Other thermal stabilizers can optionally be added to increase the thermal degradation temperature, glass transition temperature or both and can be selected from the group of SiO₂, Al₂O₃, AlN, Ag, Ni, Fe, and mixtures thereof.

In the Claims

 Please cancel claims 1-14 and 22-82 as indicated in the Request for Filing a Divisional Application filed herewith. Claims 83-92 are added in the divisional application, filed herewith. Claims 15-21 and 83-92 are pending in the present application.